1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Drain-to-source Voltage	BV _{DSS}
Drain-to-gate Voltage	
Gate-to-source Voltage	
Operating and Storage Temperatures	

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Electrical Specifications : For all specifications, $T_A = T_J = +25^{\circ}C$ unless otherwise noted.									
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions			
DC PARAMETER (Note 1 unless othe	erwise state	ed)							
Drain-to-source Breakdown Voltage	BV _{DSS}	-500			V	V _{GS} = 0V, I _D = -250 μA			
Gate Threshold Voltage	V _{GS(th)}	-1.5	_	-3.5	V	$V_{GS} = V_{DS}$, $I_D = -1 \text{ mA}$			
Change in $V_{GS(th)}$ with Temperature	$\Delta V_{GS(th)}$	_	_	-4.8	mV/°C	$V_{GS} = V_{DS}$, $I_D = -1$ mA (Note 2)			
Gate Body Leakage Current	I _{GSS}			-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$			
				-10	μA	V _{GS} = 0V, V _{DS} = Maximum Rating			
Zero Gate Voltage Drain Current	I _{DSS}			-1	mA	V _{DS} = 0.8 Maximum Rating, V _{GS} = 0V, T _A = 125°C (Note 2)			
On-state Drain Current		-75		—	mA	V _{GS} = -4.5V, V _{DS} = -15V			
On-state Drain Current	I _{D(ON)}	-200	_	—	mA	$V_{GS} = -10V, V_{DS} = -15V$			
Static Drain-to-source On-state	D			35	Ω	V_{GS} = -4.5V, I _D = -50 mA			
Resistance	R _{DS(ON)}			30		V _{GS} = –10V, I _D = –100 mA			
Change in $R_{DS(ON)}$ with Temperature	ΔR _{DS(ON)}	_	_	0.75	%/°C	V _{GS} = –10V, I _D = –100 mA (<mark>Note 2</mark>)			
AC PARAMETER (Note 2)									
Forward Transconductance	G _{FS}	150	320	—	mmho	V _{DS} = –15V, I _D = –100 mA			
Input Capacitance	C _{ISS}	_	—	190					
Common Source Output Capacitance	C _{OSS}	_	_	75	pF	V_{GS} = 0V, V_{DS} = –25V, f = 1 MHz			
Reverse Transfer Capacitance	C _{RSS}	_	_	20					
Turn-on Delay Time	t _{d(ON)}			10					
Rise Time	t _r			25	n 0	V _{DD} = –25V, I _D = –200 mA,			
Turn-off Delay Time	t _{d(OFF)}	_	_	45	ns	R _{GEN} = 25Ω			
Fall Time	t _f			25					
DIODE PARAMETER									
Diode Forward Voltage Drop	V_{SD}			-1.8	V	V _{GS} = 0V, I _{SD} = –100 mA (Note 1)			
Reverse Recovery Time	t _{rr}	_	300	_	ns	V _{GS} = 0V, I _{SD} = –100 mA (Note 2)			

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle)

2: Specification is obtained by characterization and is not 100% tested.

TEMPERATURE SPECIFICATIONS

Electrical Characteristics: Unless otherwise noted, for all specifications $T_A = T_J = +25^{\circ}C$.										
Parameter	Sym.	Sym. Min. Typ. Max.		Unit	Conditions					
TEMPERATURE RANGE										
Operating Temperature	T _A	-55		+150	°C					
Storage Temperature	Τ _S	-55	_	+150	°C					
PACKAGE THERMAL RESISTANC	E									
TO-92	θ_{JA}	_	132	_	°C/W					
SOT-89	θ_{JA}	_	133	_	°C/W					

THERMAL CHARACTERISTICS

Package	I _D (Note 1) (Continuous) (mA)	I _D (Pulsed) (mA)	Power Dissipation at T _A = 25°C (W)	I _{DR} (Note 1) (mA)	I _{DRM} (mA)
TO-92	-100	-300	0.74	-100	-300
SOT-89	-160	-800	1.6 (Note 2)	-160	-800

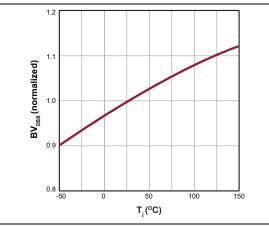
Note 1: I_D (continuous) is limited by maximum T_J .

2: Mounted on FR5 board, 25 mm x 25 mm X 1.57 mm

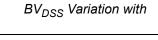
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2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.







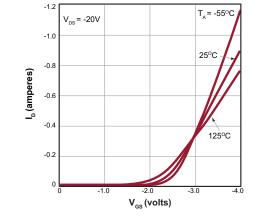
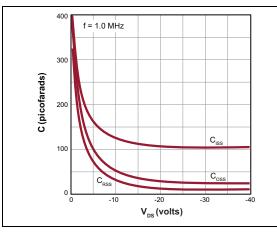


FIGURE 2-2:

Transfer Characteristics.





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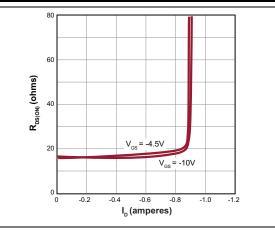


FIGURE 2-4: Current.

On-resistance vs. Drain

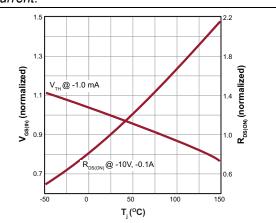


FIGURE 2-5: $V_{GS(th)}$ and $R_{DS(ON)}$ Variation with Temperature.

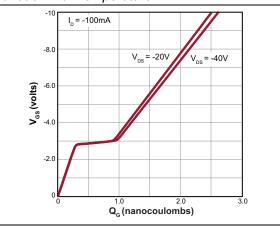
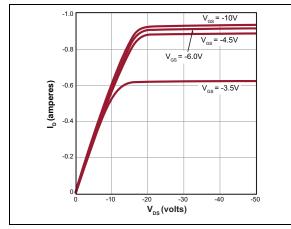


FIGURE 2-6: Characteristics.

Gate Drive Dynamic





Output Characteristics.

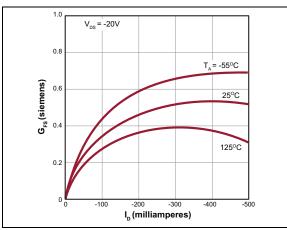


FIGURE 2-8: Transconductance vs. Drain Current.

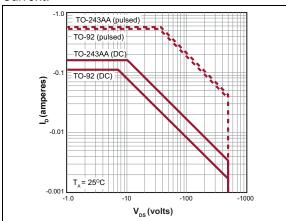


FIGURE 2-9: Maximum Rated Safe Operating Area.

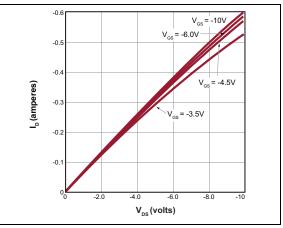


FIGURE 2-10:

Saturation Characteristics.

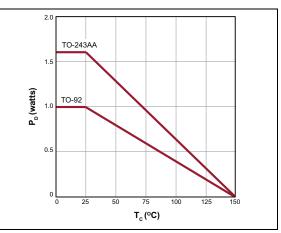


FIGURE 2-11: Temperature.

Power Dissipation vs. Case

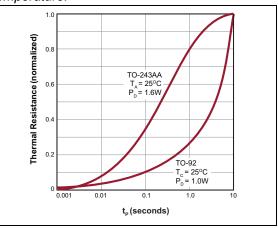


FIGURE 2-12: Thermal Response Characteristics.

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3.0 PIN DESCRIPTION

The details on the pins of VP2450 (TO-92 and SOT-89) are listed on Table 3-1. Refer to **Package Types** for the location of pins.

TABLE 3-1: PIN FUNCTION TABLE

TO-92 Pin Number	SOT-89 Pin Number	Pin Name	Description
1	3	Source	Source
2	1	Gate	Gate
3	2,4	Drain	Drain

4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for VP2450.

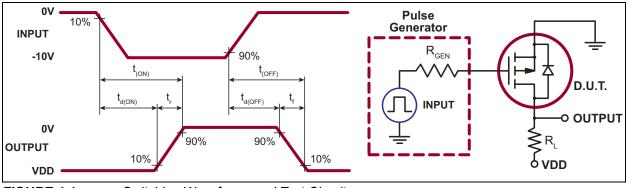


FIGURE 4-1: Switching Waveforms and Test Circuit.

PRODUCT SUMMARY

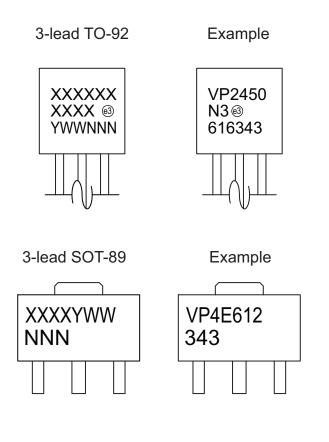
BV _{DSS} /BV _{DGS} (V)	R _{DS(ON)} (Maximum) (Ω)	I _{D(ON)} (Minimum) (mA)	V _{GS(th)} (Maximum) (V)
-500	30	-200	-0.4

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VP2450

5.0 PACKAGING INFORMATION

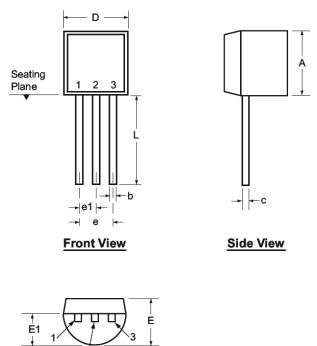
5.1 Package Marking Information



Legend:	XXX Y YY WW NNN (e3) *	Product Code or Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((3)) can be found on the outer packaging for this package.
	be carried characters	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for product code or customer-specific information. Package may or e the corporate logo.

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3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

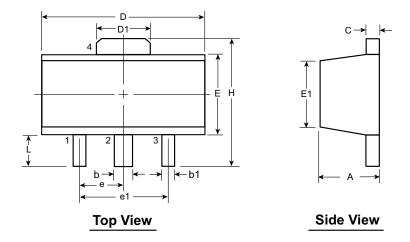
Bottom View

Symb	ol	А	b	с	D	E	E1	е	e1	L
	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
(incres)	MAX	.210	. 022 [†]	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92. * This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing. **Drawings not to scale.**

3-Lead TO-243AA (SOT-89) Package Outline (N8)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbo	ol	Α	b	b1	С	D	D1	E	E1	е	e1	н	L		
MIN	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†	1.50 3.00 BSC BSC				3.94	0.73†
Dimensions (mm)	NOM	-	-	-	-	-	-	-	-		-	-			
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29		200	4.25	1.20		

JEDEC Registration TO-243, Variation AA, Issue C, July 1986. **†** This dimension differs from the JEDEC drawing **Drawings not to scale**.

APPENDIX A: REVISION HISTORY

Revision A (September 2016)

- Converted Supertex Doc# DSFP-VP2450 to Microchip DS20005569A.
- Changed the "TO-243AA (SOT-89)" package to "SOT-89."
- Limited package options to TO-92 (1000/Bag) and SOT-89 (2000/Reel).
- Made minor text changes throughout the document.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO. XX			- <u>x</u> - <u>x</u>	Examples:				
Device	Packa Option		َ الْسُلَّةُ الْمَعْلَى الْمَعْلَى الْمَعْلَى الْمَعْلَى الْمَعْلَى الْمَعْلَى الْمَعْلَى الْمَعْلَى الْمَعْلَ Environmental Media Type	a) VP2450N3-G:	P-Channel Enhancement-Mode Vertical DMOS FET, 3-lead TO-92 Package, 1000/Bag			
				b) VP2450N8-G:	P-Channel Enhancement-Mode			
Device:	VP2450	=	P-Channel Enhancement-Mode Vertical DMOS FET		Vertical DMOS FET, 3-lead SOT-89 Package, 2000/Reel			
Packages:	N3	=	3-lead TO-92					
	N8	=	3-lead SOT-89					
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package					
Media Type:	(Blank)	=	1000/Bag for an N3 Package					
	(-)		2000/Reel for an N8 Package					
			-					
I								

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